

TK1020 - Parmi HS70 3D Solder Paste Inspector (2011)

Model: HS70 3D Solder Paste Inspector

SKU:

Year: 2011



Description:

PARMI HS70 3D Solder Paste Inspection Machine (2011)

Brand: Parmi

Model: HS70 3D Solder Paste Inspection Machine (SPI)

Serial #: H7S03811F

Year: 2011

Machine Specifications:

Software Version: Parmi 3D SPI v1.5.1.2

Conveyor Inspection Program: Single Lane 1 stage conveyor

System Diagnosis Up/down stream Interface:SMEMA II

Measurement:

Measuring Principle: Shadow free Dual Laser Optical Triangulation

Inspection Type: Height, Area, Volume, Offset, Bridge, Shape, Warpage, PCB shrink

Camera Type RSC VI Specifications:

X-Y Resolution: 18x9 j/m

Height Resolution: 0.1 j/m

Max. Paste Height & Size: 1000 mm / 20x20 mm

Min. Paste Size & Pitch: 150x150 mm / 100 mm

Inspection Speed: 80 sg.cm/sec

Height Accuracy: 2 mm. on a certification target

Height Repeatability: 3 Sigma (1 mm, on a certification target

Area Repeatability: 3 Sigma (1%, on a certification target

Volume Repeatability: 3 Sigma (1%, on a certification target

Board Specification:

Gage R&R Maximum & Minimum Board Size: « 5 % - 430 x350

Maximum Board Warp: ±5 mm

Board Thickness: 0.4 to 4 mm

Board Edge Clearance (TOP/Bottom): 2.5/4mm

Underside Clearance: 23 mm

System Dimensions:

Dimensions (WxDxH): 970 x 1195 x 1535 mm

Weight: 800 kg

Conveyor Height: 890 - 965 mm [SMEMA]

Load, Unload Time: 3.0 sec

Flow Direction: Left-Right or Right-Left (Automatic)(Optional)

Hardware System:

Conveyor Width Adjusting X-Y-Z robot: Auto Adjustable - Sensor head move in X-Y-Z axis

Computer: Pentium IV Quad Core, 8GB Memory, MS-Windows XP Professional 64bit

Power Supplies: Electric - AC 220V, 50/60 Hz, Pneumatic - 5Kgf/sq cm

